SCHS228B - SEPTEMBER 1998 - REVISED MARCH 2004

- AC Types Feature 1.5-V to 5.5-V Operation and Balanced Noise Immunity at 30% of the Supply Voltage
- Speed of Bipolar F, AS, and S, With Significantly Reduced Power Consumption
- Greater Noise Immunity Than Standard Inverters
- Operates With Much Slower Than Standard Input Rise and Fall Slew Rates
- Balanced Propagation Delays
- ±24-mA Output Drive Current
  Fanout to 15 F Devices
- SCR Latchup-Resistant CMOS Process and Circuit Design
- Exceeds 2-kV ESD Protection Per MIL-STD-883, Method 3015

## description/ordering information

E OR M PACKAGE (TOP VIEW)							
1A [	1	υ	14	Vcc			
1Y [	2		13	] V <sub>CC</sub> ] 6A			
2A [	3		12	]6Y			
2Y [	4		11	] 5A			
3A [	5		10	] 5Y			
3Y [	6		9	] 4A			
GND [	7		8	] 4Y			

The CD74AC14 contains six independent inverters. This device performs the Boolean function  $Y = \overline{A}$ .

Each circuit functions as an independent inverter, but because of the Schmitt action, the inverters have different input threshold levels for positive-going ( $V_{T+}$ ) and negative-going ( $V_{T-}$ ) signals.

TA	PACKA	GE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING						
	PDIP – E	Tube	CD74AC14E	CD74AC14E						
–55°C to 125°C	SOIC – M	Tube	CD74AC14M	AC14M						
	3010 – M	Tape and reel	CD74AC14M96							

## **ORDERING INFORMATION**

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE						
(each inverter)						
INIDUT	OUTDUT					

INPUT	OUTPUT
Α	Y
Н	L
L	Н

logic diagram, each inverter (positive logic)





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SCHS228B - SEPTEMBER 1998 - REVISED MARCH 2004

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, V <sub>CC</sub>	–0.5 V to 6 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) (see Note 1)	
Output clamp current, $I_{OK}$ (V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub> ) (see Note 1)	
Continuous output current, $I_O (V_O = 0 \text{ to } V_{CC})$	±50 mA
Continuous current through V <sub>CC</sub> or GND	±100 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2): E package	80°C/W
M package	
Storage temperature range, T <sub>stg</sub>	. −65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

#### recommended operating conditions (see Note 3)

			T <sub>A</sub> = 2	25°C	–55° 125		–40°( 85°		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
VCC	Supply voltage		1.5	5.5	1.5	5.5	1.5	5.5	V
VI	Input voltage		0	VCC	0	VCC	0	VCC	V
Vo	Output voltage		0	VCC	0	VCC	0	VCC	V
IOH	High-level output current	$V_{CC}$ = 4.5 V to 5.5 V		-24		-24		-24	mA
IOL	Low-level output current	$V_{CC}$ = 4.5 V to 5.5 V		24		24		24	mA

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



SCHS228B - SEPTEMBER 1998 - REVISED MARCH 2004

PARAMETER	TEST CO	v <sub>cc</sub>	T <sub>A</sub> = 25°C		–55°C to 125°C		–40°C to 85°C		UNIT	
			MIN	MAX	MIN	MAX	MIN	MAX		
VT+ Positive-going threshold		5 V	2.6	3.4	2.6	3.4	2.6	3.4	V	
VT– Negative-going threshold		5 V	1.6	2.4	1.6	2.4	1.6	2.4	V	
∆V <sub>T</sub> Hysteresis (V <sub>T+</sub> – V <sub>T−</sub> )			5 V	0.5		0.5		0.5		V
VOH			1.5 V	1.4		1.4		1.4		
	$V_I = V_{T+}$	I <sub>OH</sub> = -50 μA	3 V	2.9		2.9		2.9		V
			4.5 V	4.4		4.4		4.4		
		$I_{OH} = -4 \text{ mA}$	3 V	2.58		2.4		2.48		
		I <sub>OH</sub> = -24 mA	4.5 V	3.94		3.7		3.8		7
		I <sub>OH</sub> = -50 mA <sup>†</sup>	5.5 V			3.85				
		I <sub>OH</sub> = -75 mA†	5.5 V					3.85		
			1.5 V		0.1		0.1		0.1	
		I <sub>OL</sub> = 50 μA	3 V		0.1		0.1		0.1	
			4.5 V		0.1		0.1		0.1	
VOL	$V_{I} = V_{T-}$	I <sub>OL</sub> = 12 mA	3 V		0.36		0.5		0.44	V
		I <sub>OL</sub> = 24 mA	4.5 V		0.36		0.5		0.44	
		$I_{OL} = 50 \text{ mA}^{\dagger}$	5.5 V				1.65			
		$I_{OL} = 75 \text{ mA}^{\dagger}$	5.5 V						1.65	
l	$V_I = V_{CC} \text{ or } GND$		5.5 V		±0.1		±1		±1	μΑ
ICC	$V_I = V_{CC}$ or GND,	I <sub>O</sub> = 0	5.5 V		4		80		40	μΑ
Ci					10		10		10	pF

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

<sup>†</sup> Test one output at a time, not exceeding 1-second duration. Measurement is made by forcing indicated current and measuring voltage to minimize power dissipation. Test verifies a minimum 50-Ω transmission-line drive capability at 85°C and 75-Ω transmission-line drive capability at 125°C.

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V, $C_L$ = 50 pF (unless otherwise noted) (see Figure 1)

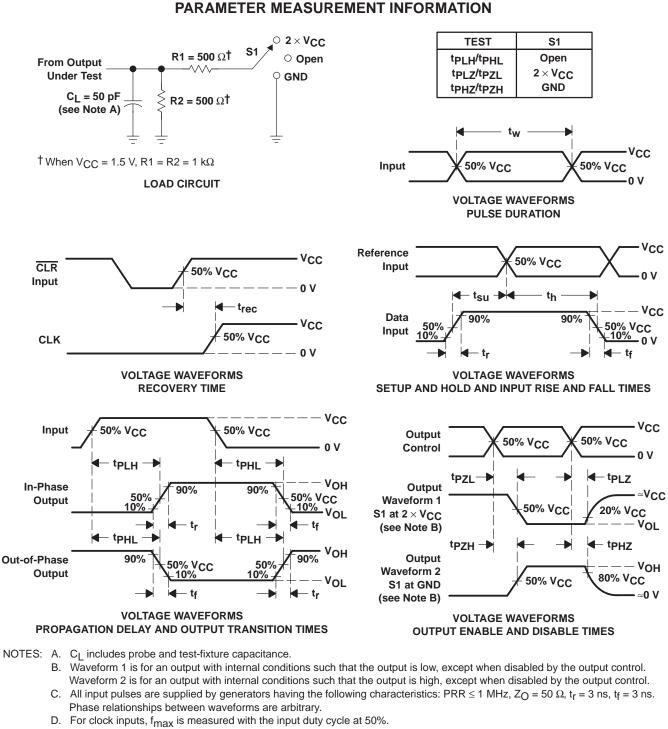
PARAMETER	RAMETER FROM TO (INPUT) (OUTPUT)		–55°C TO 125°C		–40°C TO 85°C		UNIT
	(INFOT)	(001201)	MIN	MAX	MIN	MAX	
<sup>t</sup> PLH	A	X	2.6	10.5	2.7	9.5	
<sup>t</sup> PHL		Ý	2.6	10.5	2.7	9.5	ns

## operating characteristics, V\_CC = 5 V, T\_A = 25°C

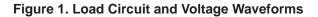
	PARAMETER	TYP	UNIT
C <sub>pd</sub>	Power dissipation capacitance	45	pF



SCHS228B - SEPTEMBER 1998 - REVISED MARCH 2004



- E. The outputs are measured one at a time, with one input transition per measurement.
- F.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{Dd}$ .
- G.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
- H. tpLz and tpHz are the same as tdis.





## PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
CD74AC14E	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
CD74AC14M	ACTIVE	SOIC	D	14	50	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM
CD74AC14M96	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

None: Not yet available Lead (Pb-Free).

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Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.

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# N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- $\triangle$  The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-012 variation AB.



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